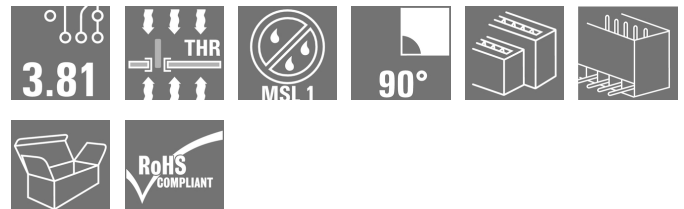


OMNIMATE Signal - series BC/SC 3.81 SCDN-THR 3.81/08/90G 3.2SN BK BX

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com

Product image



Similar to illustration

Extra flat high-temperature-resistant two-tier SCDN-THR pin header for reflow soldering.

- Two compact interfaces are used with the flat BCF 3.81 (PUSH IN) socket block.
- Available as 90° (recumbent).
- Connections on a single level, allowing access that is flush over the front board.
- Space for labelling and coding
- Packed in cardboard box.

Weidmüller's 3.81-mm-pitch (0.15 inch) plug-in connectors are compatible with the layouts of standard connectors and offer space for labelling and coding.

General ordering data

Type	SCDN-THR 3.81/08/90G 3.2SN BK BX
Order No.	1038970000
Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 3.81 mm, Number of poles: 8, 90°, Solder pin length (l): 3.2 mm, tinned, black, Box
GTIN (EAN)	4032248772315
Qty.	50 pc(s).
Product data	IEC: 320 V / 17.5 A UL: 300 V / 11 A
Packaging	Box

Creation date August 8, 2020 1:24:06 AM CEST

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Technical data**Dimensions and weights**

Width	16.63	Width (inches)	0.655 inch
Height	18.4 mm	Height (inches)	0.724 inch
Height of lowest version	15.2 mm	Depth	13.3 mm
Depth (inches)	0.524 inch	Net weight	3.72 g

System specifications

Product family	OMNIMATE Signal - series BC/SC 3.81	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.81 mm
Pitch in inches (P)	0.15 inch	Outgoing elbow	90°
Number of poles	8	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin length tolerance	+0,02 / -0,02 mm
Tolerance of solder pin position	± 0.1 mm	Solder pin dimensions	d = 1.0 mm, Octagonal
Solder pin dimensions = d tolerance	0 / -0,03 mm	Solder eyelet hole diameter (D)	1.3 mm
Solder eyelet hole diameter tolerance (D)+	0,1 mm	Outside diameter of solder pad	2.1 mm
Template aperture diameter	1.9 mm	L1 in mm	11.43 mm
L1 in inches	0.45 inch	Number of rows	2
Pin series quantity	2	Touch-safe protection acc. to DIN VDE 57 106	Safe from finger touch
Touch-safe protection acc. to DIN VDE 0470	IP 20	Volume resistance	≤ 5mΩ
Can be coded	Yes	Plugging cycles	25

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Insulation strength	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
GWIT	930 °C	GWFI	960 °C
Contact material	Copper alloy	Contact surface	tinned
Storage temperature, min.	-40 °C	Storage temperature, max.	70 °C
Operating temperature, min.	-50 °C	Operating temperature, max.	120 °C
Temperature range, installation, min.	-25 °C	Temperature range, installation, max.	120 °C

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	17.5 A
Rated current, max. number of poles (Tu=20°C)	13.2 A	Rated current, min. number of poles (Tu=40°C)	17 A
Rated current, max. number of poles (Tu=40°C)	12.2 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 76 A

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	11 A	Rated current (Use group D / CSA)	11 A

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Technical data**Rated data acc. to UL 1059**

Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group B / UL 1059)	11 A	Rated current (Use group D / UL 1059)	11 A

Packing

Packaging	Box	VPE length	25 mm
VPE width	140 mm	VPE height	255 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
eClass 9.0	27-44-04-02	eClass 9.1	27-44-04-02
eClass 10.0	27-44-04-02		

Notes

Notes	<ul style="list-style-type: none"> Rated current related to rated cross-section & min. No. of poles. Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. P on drawing = pitch Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months
IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Approvals

Approvals



ROHS Conform

Downloads

Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Brochure/Catalogue	FL DRIVES EN MB DEVICE MANUF. EN FL DRIVES DE CAT 2 PORTFOLIOGUIDE EN FL BUILDING SAFETY EN FL APPL LED LIGHTING EN FLIndustr.CONTROLS EN FL MACHINE SAFETY EN FL HEATING ELECTR EN FL APPL INVERTER EN FL_BASE_STATION EN FL ELEVATOR EN FL POWER SUPPLY EN FL 72H SAMPLE SER EN PO OMNIMATE EN
Engineering Data	STEP
White paper surface mount technology	Download Whitepaper

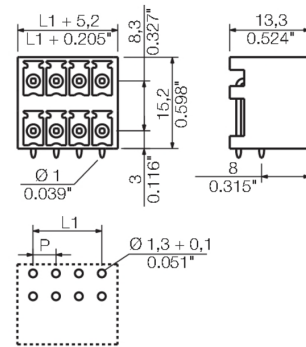
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Catalogue status 24.07.2020 / We reserve the right to make technical changes.

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Dimensional drawing



Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is ‚activated‘. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.